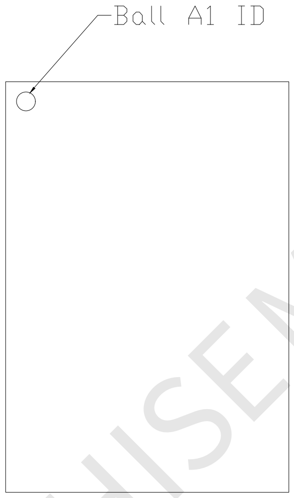
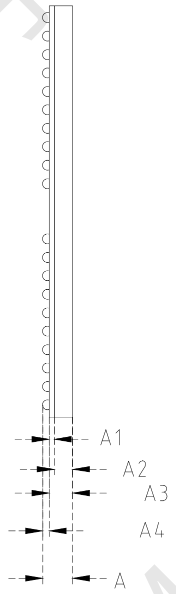
RoHS

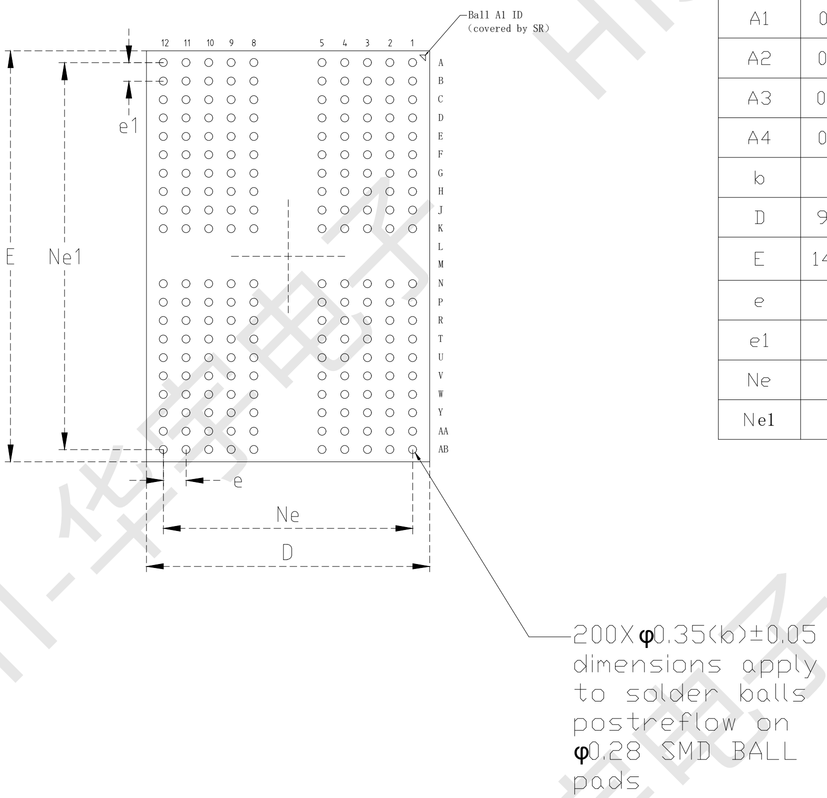
TOP VIEW
正视图



SIDE VIEW
侧视图



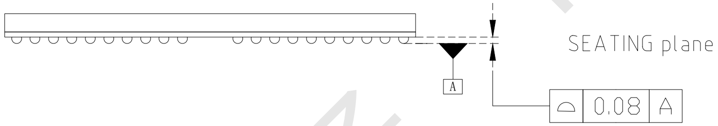
BOTTOM VIEW
背视图



200Xφ0.35(b)±0.05 dimensions apply to solder balls postreflow on φ0.28 SMD BALL pads

机械尺寸/mm			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	1.00	1.100	1.200
A1	0.150	0.180	0.210
A2	0.060	0.650	0.700
A3	0.078	0.830	0.880
A4	0.175	0.225	0.275
b	0.350 REF		
D	9.900	10.000	10.100
E	14.400	14.500	14.600
e	0.650 BSC		
e1	0.800 BSC		
Ne	8.800 REF		
Ne1	13.650 REF		

SIDE VIEW
侧视图



池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

HY-POD-BGA0114

PACKAGE OUTLINE DIMENSIONS
FBGA200B(14.5X10x1.1-P0.65)

页数 page	单位 unit	比例 scale	视图 view
1	mm	1:1	

制图: Draw	NINGLIN 2025.11.25
制图核查: Drawing review	
审核: Checker	
核准: Approved	